

N-Channel Enhancement Mode Power MOSFET

**Description**

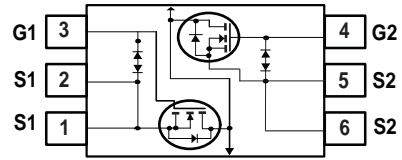
The PED2316N uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected.

**General Features**

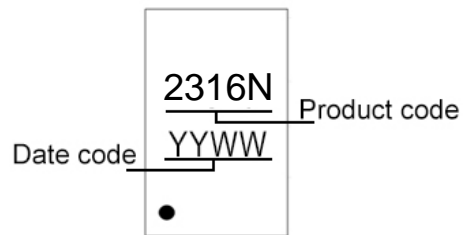
- $V_{DS} = 20V, I_D = 13A$   
 $R_{DS(ON)} = 6.5m\Omega @ V_{GS}=4.5V$   
 $R_{DS(ON)} = 6.6m\Omega @ V_{GS}=4.2V$   
 $R_{DS(ON)} = 6.8m\Omega @ V_{GS}=3.8V$   
 $R_{DS(ON)} = 8.6m\Omega @ V_{GS}=2.5V$   
 ESD Rating: 2000V HBM
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

**Application**

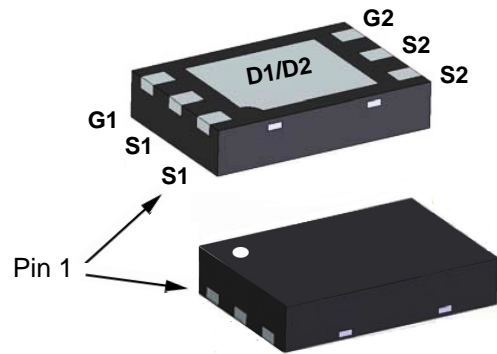
- PWM application
- Load switch



Schematic diagram



Marking Description



DFN2x3-6L Pin assignment and bottom/top view

**Absolute Maximum Ratings (TA=25°C unless otherwise noted)**

| Parameter  | Symbol         | Limit      | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage                             | $V_{DS}$       | 20         | V    |
| Gate-Source Voltage                              | $V_{GS}$       | ±12        | V    |
| Drain Current-Continuous                         | $I_D$          | 13         | A    |
| Drain Current-Pulsed (Note 1)                    | $I_{DM}$       | 70         | A    |
| Maximum Power Dissipation                        | $P_D$          | 1.5        | W    |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 To 150 | °C   |

**Thermal Characteristic**

|  |                 |    |      |
|--|-----------------|----|------|
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 83 | °C/W |
|--|-----------------|----|------|

**Electrical Characteristics (TA=25°C unless otherwise noted)**

| Parameter                       | Symbol     | Condition                 | Min | Typ | Max | Unit    |
|---------------------------------|------------|---------------------------|-----|-----|-----|---------|
| <b>Off Characteristics</b>      |            |                           |     |     |     |         |
| Drain-Source Breakdown Voltage  | $BV_{DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 20  | 22  | -   | V       |
| Zero Gate Voltage Drain Current | $I_{DSS}$  | $V_{DS}=20V, V_{GS}=0V$   | -   | -   | 1   | $\mu A$ |

| Parameter                                 | Symbol       | Condition  | Min  | Typ  | Max      | Unit       |
|---|--------------|--|------|------|----------|------------|
| Gate-Body Leakage Current                 | $I_{GSS}$    | $V_{GS}=\pm 12V, V_{DS}=0V$                                  | -    | -    | $\pm 10$ | $\mu A$    |
| <b>On Characteristics (Note 3)</b>        |              |  |      |      |          |            |
| Gate Threshold Voltage                    | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$                                | 0.45 | 0.8  | 1.2      | V          |
| Drain-Source On-State Resistance          | $R_{DS(on)}$ | $V_{GS}=4.5V, I_D=5.5A$                                      | 6.0  | 6.5  | 7.5      | m $\Omega$ |
|   |              | $V_{GS}=4.2V, I_D=5.5A$                                      | 6.1  | 6.6  | 8.0      | m $\Omega$ |
|   |              | $V_{GS}=3.8V, I_D=5.5A$                                      | 6.2  | 6.8  | 8.6      | m $\Omega$ |
|   |              | $V_{GS}=2.5V, I_D=5.0A$                                      | 7.8  | 8.6  | 10       | m $\Omega$ |
| Forward Transconductance                  | $g_{FS}$     | $V_{DS}=5V, I_D=5A$  | -    | 20   | -        | S          |
| <b>Dynamic Characteristics (Note4)</b>    |              |  |      |      |          |            |
| Input Capacitance                         | $C_{iss}$    | $V_{DS}=10V, V_{GS}=0V,$<br>$F=1.0MHz$                       | -    | 1767 | -        | PF         |
| Output Capacitance                        | $C_{oss}$    |  | -    | 184  | -        | PF         |
| Reverse Transfer Capacitance              | $C_{rss}$    |  | -    | 155  | -        | PF         |
| <b>Switching Characteristics (Note 4)</b> |              |  |      |      |          |            |
| Turn-on Delay Time                        | $t_{d(on)}$  | $V_{DD}=10V, R_L=1.35\Omega$<br>$V_{GS}=5V, R_{GEN}=3\Omega$ | -    | 10.2 |          | nS         |
| Turn-on Rise Time                         | $t_r$        |  | -    | 41   |          | nS         |
| Turn-Off Delay Time                       | $t_{d(off)}$ |  | -    | 67   |          | nS         |
| Turn-Off Fall Time                        | $t_f$        |  | -    | 31   |          | nS         |
| Total Gate Charge                         | $Q_g$        | $V_{DS}=10V, I_D=7A,$<br>$V_{GS}=4.5V$                       | -    | 23   |          | nC         |
| Gate-Source Charge                        | $Q_{gs}$     |  | -    | 3.5  | -        | nC         |
| Gate-Drain Charge                         | $Q_{gd}$     |  | -    | 8.4  | -        | nC         |
| <b>Drain-Source Diode Characteristics</b> |              |  |      |      |          |            |
| Diode Forward Voltage (Note 3)            | $V_{SD}$     | $V_{GS}=0V, I_S=1A$  | -    | -    | 1.2      | V          |
| Diode Forward Current (Note 2)            | $I_S$        |  | -    | -    | 7        | A          |

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

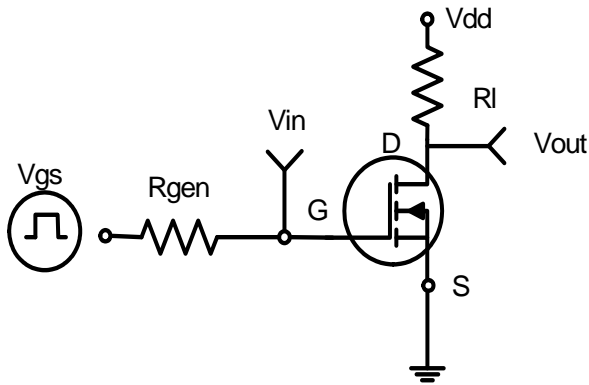


Figure 1: Switching Test Circuit

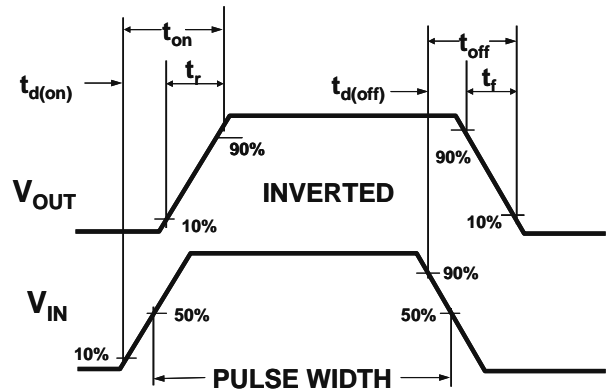


Figure 2: Switching Waveforms

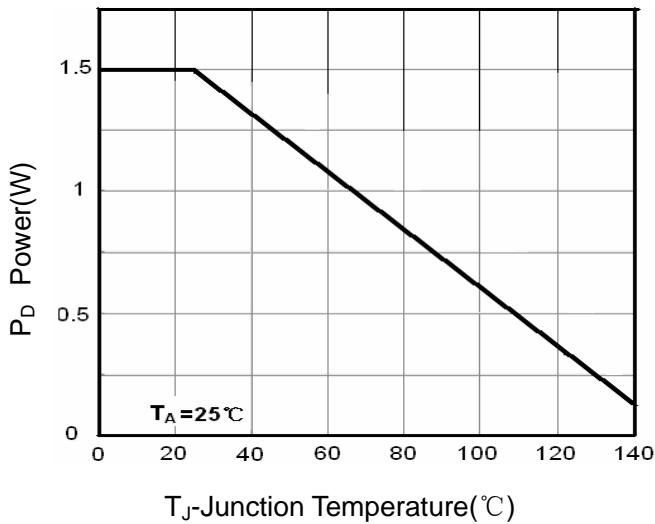


Figure 3 Power Dissipation

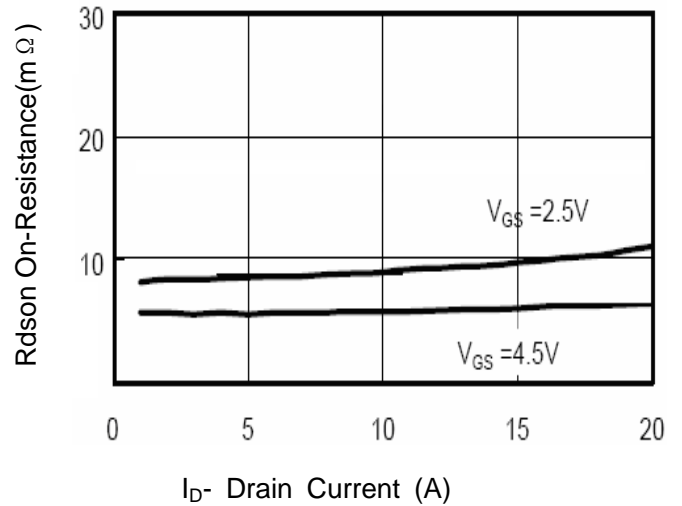


Figure 4 Drain-Source On-Resistance

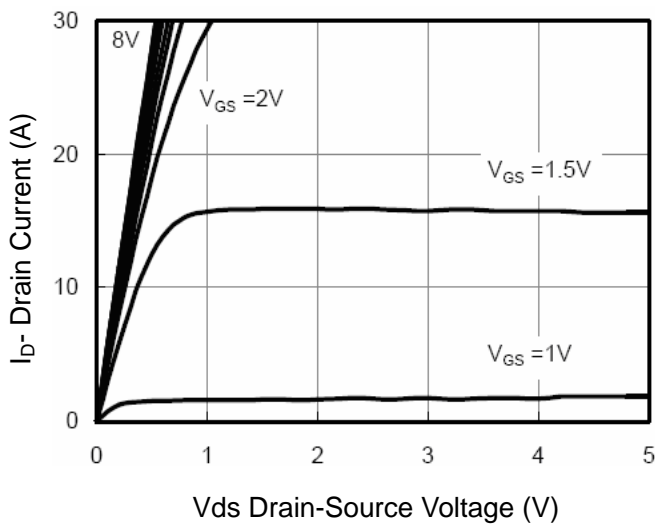


Figure 5 Output CHARACTERISTICS

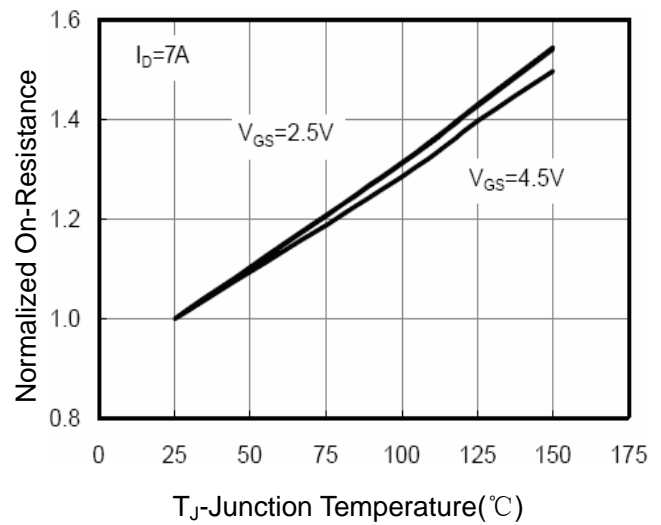


Figure 6 Drain-Source On-Resistance

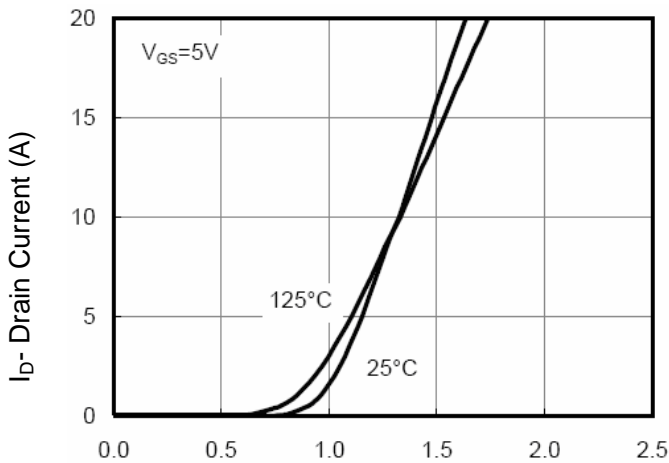


Figure 7 Transfer Characteristics

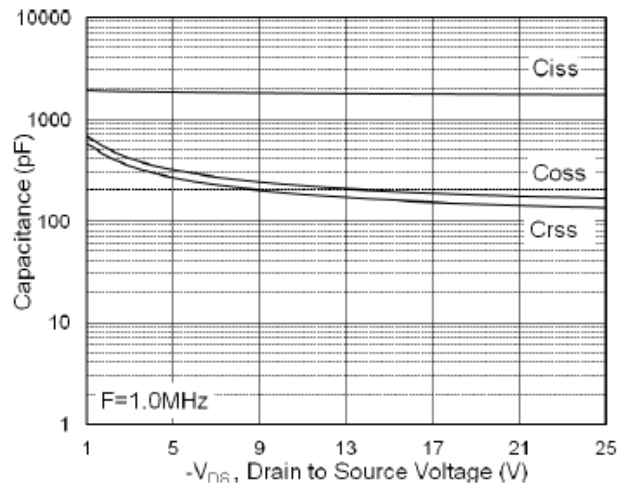


Figure 8 Capacitance vs Vds

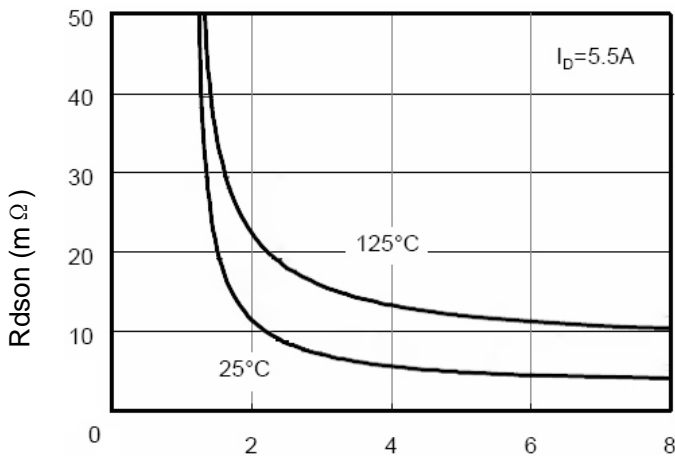


Figure 9 Rdson vs Vgs

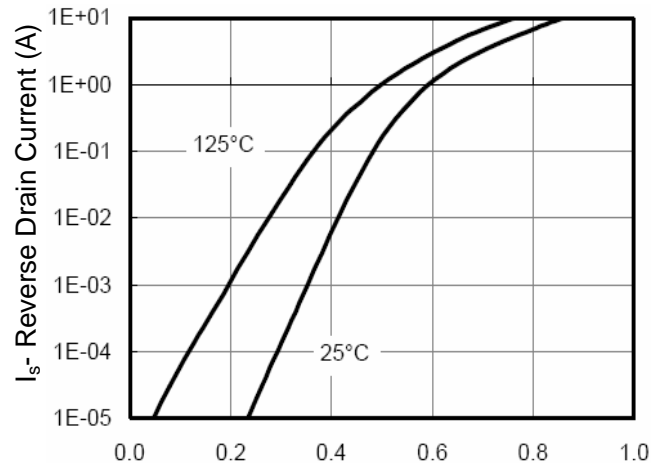


Figure 10 Capacitance vs Vds

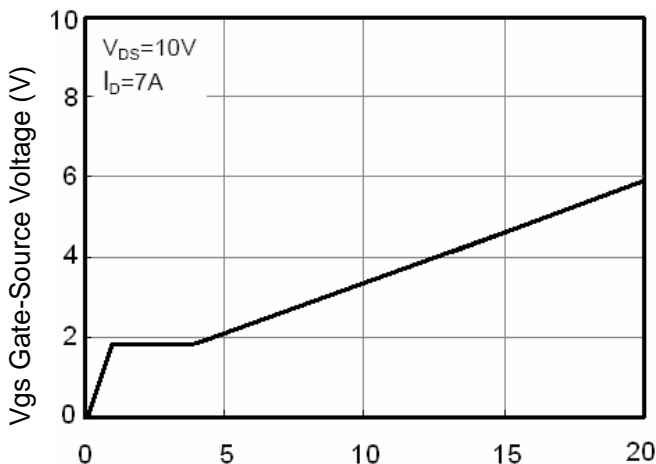


Figure 11 Gate Charge

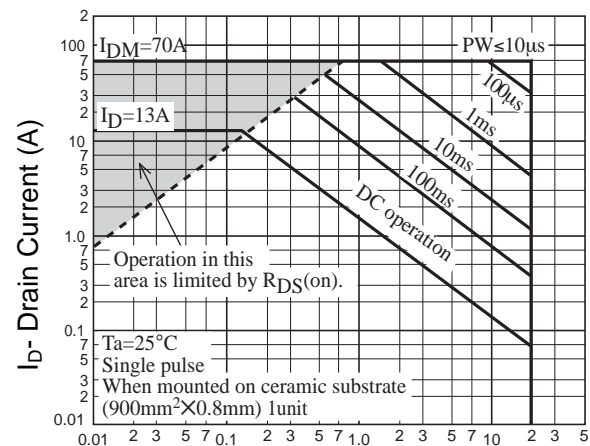
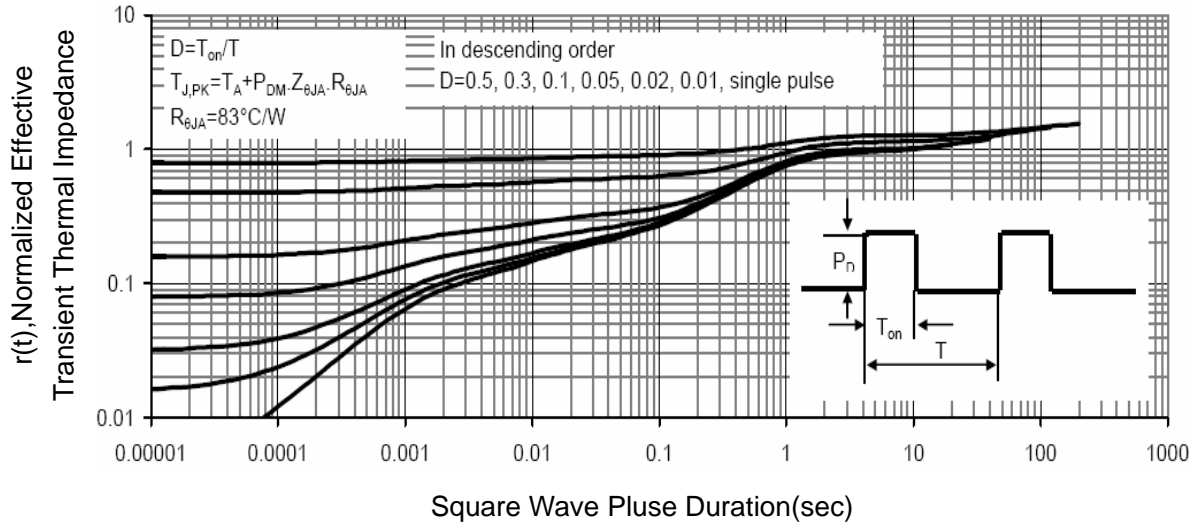
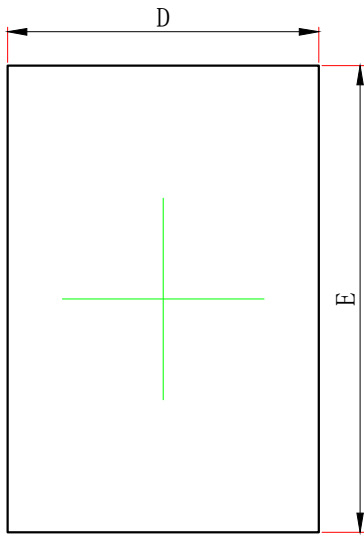


Figure 12 Safe Operation Area

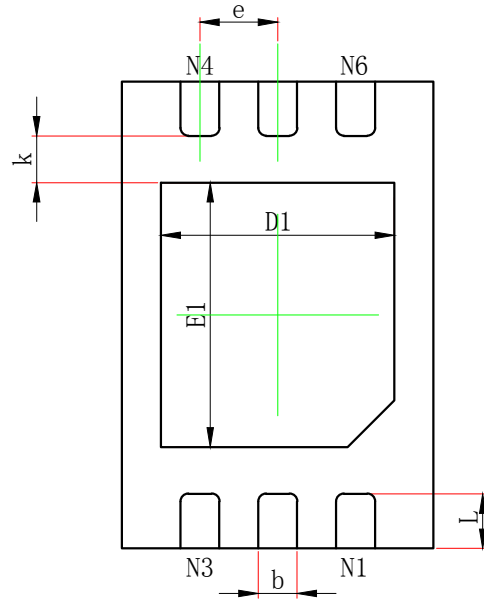


**Figure 13 Normalized Maximum Transient Thermal Impedance**

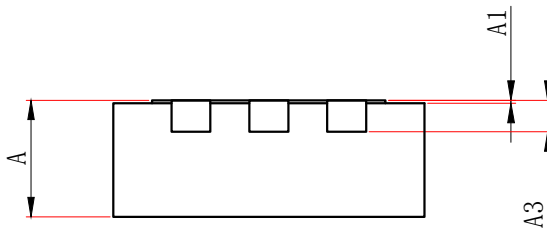
DFNWB2 × 3-6L (P0.50T0.75) PACKAGE OUTLINE DIMENSIONS



TOPVIEW



BOTTOMVIEW



SIDEVIEW

| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min.                      | Max.  | Min.                 | Max.  |
| A      | 0.700                     | 0.800 | 0.028                | 0.031 |
| A1     | 0.000                     | 0.050 | 0.000                | 0.002 |
| A3     | 0.203REF.                 |       | 0.008REF.            |       |
| D      | 1.950                     | 2.050 | 0.077                | 0.081 |
| E      | 2.950                     | 3.050 | 0.116                | 0.120 |
| D1     | 1.450                     | 1.550 | 0.057                | 0.061 |
| E1     | 1.650                     | 1.750 | 0.065                | 0.069 |
| k      | 0.200MIN.                 |       | 0.008MIN.            |       |
| b      | 0.200                     | 0.300 | 0.008                | 0.012 |
| e      | 0.500TYP.                 |       | 0.020TYP.            |       |
| L      | 0.300                     | 0.400 | 0.012                | 0.016 |